CLAIMS

1. (Amended) A board for printed wiring made by treating the surface of a board whereon a conductor wiring is to be formed by one of the following surface treatment methods:

(1) surface roughening treatment for achieving center line average roughness Ra in a range from 30 to 300 nm;

(2) plasma treatment;

(3) surface roughening treatment for achieving center line average roughness Ra in a range from 30 to 300 nm followed by plasma treatment, or

(4) surface roughening treatment for achieving center line average roughness Ra in a range from 30 to 300 nm followed by the step of forming a porous metal layer made of at least one kind of metal selected from among the group consisting of Al, Cr, Co, Ni, Cu and Ag, by sputtering.

2. (Deleted)

3. (Deleted)

4. (Deleted)

5. (Deleted)

6. (Deleted)

7. (Deleted)

8. (Deleted)

9. (Deleted)

10. (Amended) A printed wiring board made by forming a conductor wiring by printing an electrically conductive paste containing metal particles M used as an electrically conductive filler and a binder B in volume ratio of M/B = 1/1 to 1.9/1 on the surface of the board for printed wiring of claim 1 whereon the surface treatment has been applied, etching the surface of the conductor wiring on at least a portion thereof used for connection with an external circuit so as to expose the metal particles on the surface, and forming a plating layer by electroless plating on the surface of the conductor wiring where the metal particles have been exposed by etching.

11. (Deleted)

12. (Deleted)